

10/100BASE-T TRANSFORMER MODEL NO.: HD-252

FEATURE:

- RoHS Compliant
- RoHS peak solder rating 260°C 3~5 sec
- Meets IEEE802.3af specification
- Designed to meet IR requirement
- Operating temp. : -40°C ~ +85°C

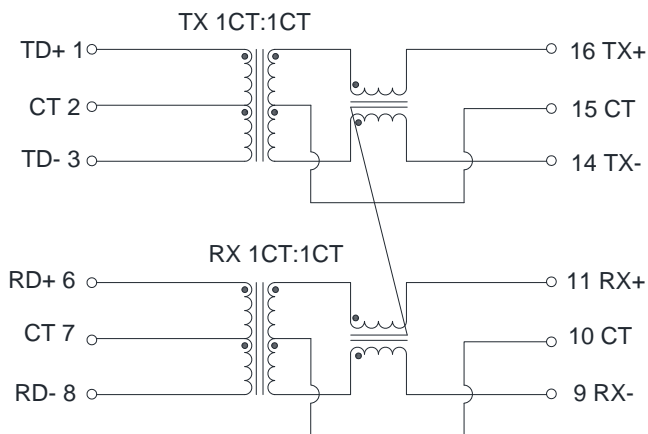
SPECIFICATIONS : @ 25°C

OCL : 350 uH Min @100kHz ,100mv

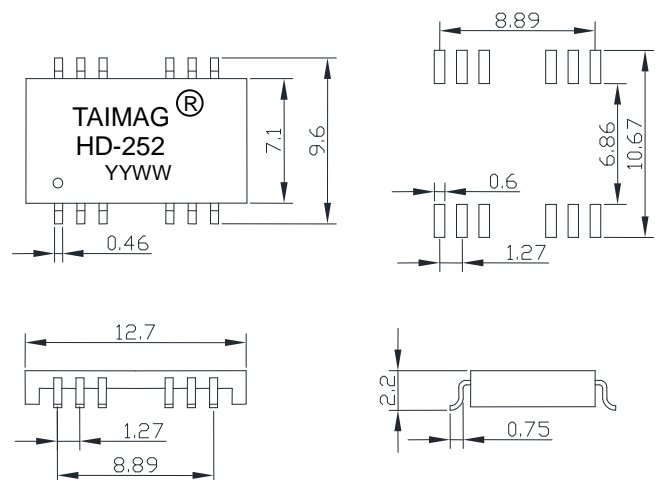
DCR : 1.0Ω Max.

Turns Ratio (±3%)	Insertion Loss MHz (dB MAX)	Return Loss MHz (dB MIN)				Cross Talk MHz (dB MIN)			CMRR			HIPOT (VAC)
		1~30	40	50	60-80	30	60	100	30	60	100	
1CT:1CT	1 ~ 100	-16	-14	-13	-12	-45	-45	-35	-43	-37	-33	1500
	-1.2											

SCHEMATICS :



DIMENSION :mm ; TOLERANCE :±0.25



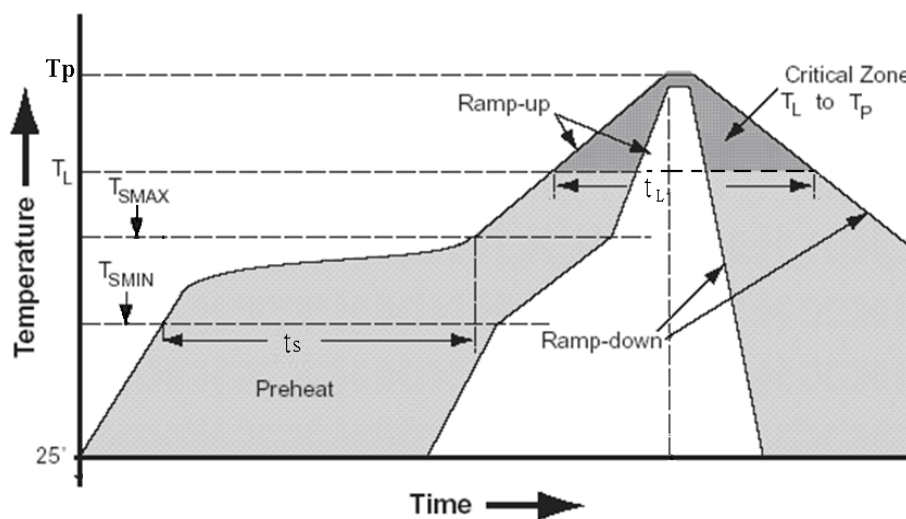
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Solder Reflow profile for Lead-Free packages.
Package Peak Reflow Temperatures

Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate(T_L to T_P)	3°C / Second Max.	
Preheat Temperature Min.(T_s min.) Temperature Max.(T_s max.) Time (min to max) (t_s)	150 °C 200 °C 60-180 sec	
T_s max. to T_L Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature (T_L) Time (t_L)	200°C 60-90 sec	
Peak Temperature (T_p) Time within 5 °C of actual peak Temp.	260 +0 / -5 °C 3 to 5 Sec	250 +0 / -5 °C 20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutes Max.	

PROFILE



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PACKING

1. Tape & Reel: 2000 pcs / Reel, 10000 pcs / Carton
2. Dry Pack: 1 pc.
 Product Description: 5g Silica Gel Desiccant
 PH: 4-8
 Package Materials: Paper (Length 6.5±1cm , Width 5±1cm)
3. Reel: Vacuum Packed
4. Seal as per JEDEC

